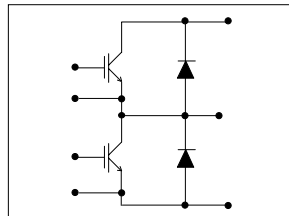


Features

- UltraFast Non Punch Through (NPT) Technology
- Positive $V_{CE(ON)}$ Temperature Coefficient
- 10 μ s Short Circuit Capability
- HEXFRED™ Antiparallel Diodes with UltraSoft Reverse Recovery
- Low Diode V_F
- Square RBSOA
- Aluminum Nitride DBC
- Optional SMT Thermistor Inside
- Very Low Stray Inductance Design for High Speed Operation

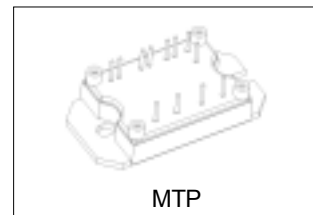


$$V_{CES} = 1200V$$

$$V_{CE(on) \text{ typ.}} = 3.1V @$$

$$V_{GE} = 15V, I_C = 40A$$

$$T_C = 25^\circ C$$



Benefits

- Optimized for Welding, UPS and SMPS Applications
- Rugged with UltraFast Performance
- Benchmark Efficiency above 20KHz
- Outstanding ZVS and Hard Switching Operation
- Low EMI, requires Less Snubbing
- Excellent Current Sharing in Parallel Operation
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Very Low Junction-to-Case Thermal Resistance

Absolute Maximum Ratings

Parameters		Max	Units	
V_{CES}	Collector-to-Emitter Voltage	1200	V	
I_C	Continuous Collector Current	@ $T_C = 25^\circ C$	80	
		@ $T_C = 100^\circ C$	40	
I_{CM}	Pulsed Collector Current	200	A	
I_{LM}	Peak Switching Current	200		
I_F	Diode Continuous Forward Current	@ $T_C = 100^\circ C$		20
I_{FM}	Peak Diode Forward Current	120		
V_{GE}	Gate-to-Emitter Voltage	± 20		V
V_{ISOL}	RMS Isolation Voltage, Any Terminal to Case, t = 1 min	2500	W	
P_D	Maximum Power Dissipation	@ $T_C = 25^\circ C$		800
		@ $T_C = 100^\circ C$	330	

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
$V_{(BR)CES}$ Collector-to-Emitter Breakdown Voltage	1200			V	$V_{GE} = 0V, I_C = 250\mu A$
$V_{CE(on)}$ Collector-to-Emitter Voltage		3.1			$V_{GE} = 15V, I_C = 40A$
		3.9			$V_{GE} = 15V, I_C = 40A, T_J = 125^\circ\text{C}$
$V_{GE(th)}$ Gate Threshold Voltage	4.4		6		$I_C = 0.5mA$
$\Delta V_{GE(th)}/\Delta T_J$ Temperature Coeff. of Threshold Voltage		-		mV/°C	
g_{fe} Forward Transconductance		-		S	
I_{CES} Collector-to-Emitter Leaking Current			250	μA	$V_{GE} = 0V, V_{CE} = 1200V$
V_{FM} Diode Forward Voltage Drop		2.0		V	$I_F = 40A, V_{GE} = 0V$
		2.35			$I_F = 40A, V_{GE} = 0V, T_J = 125^\circ\text{C}$
I_{GES} Gate-to-Emitter Leakage Current			± 200	nA	$V_{GE} = \pm 20V$

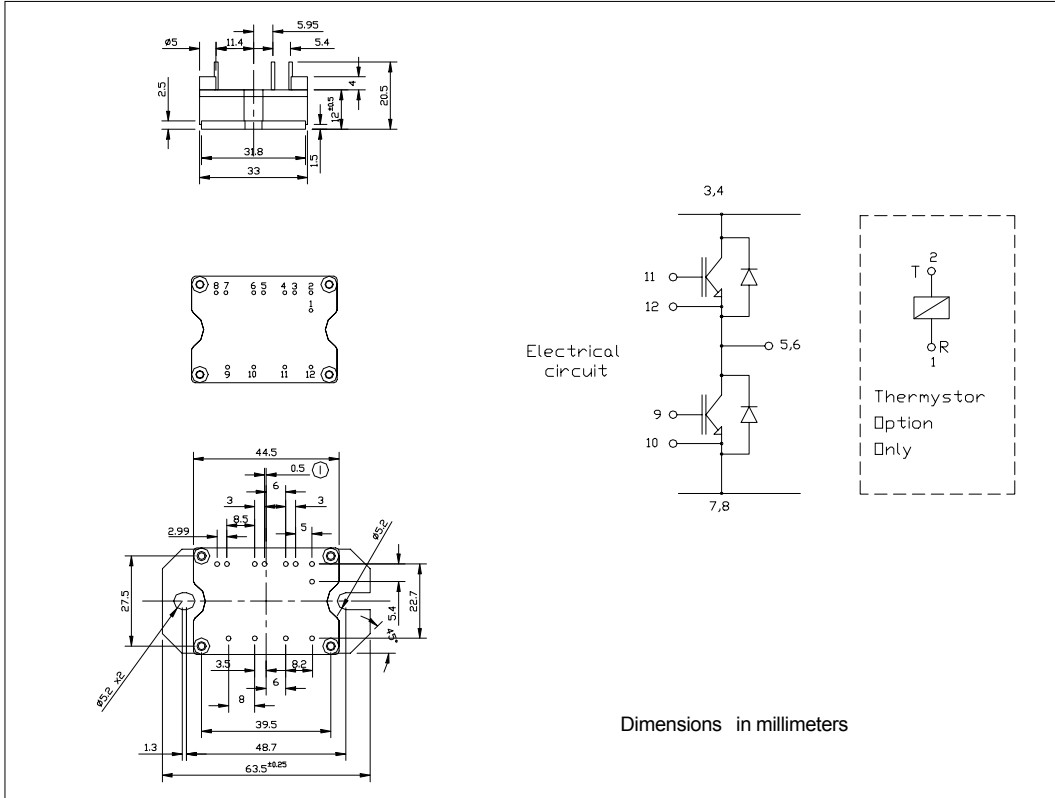
Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
Q_g Total Gate Charge (turn-on)		395		nC	$I_C = 40A$
Q_{ge} Gate-Emitter Charge (turn-on)		56			$V_{CC} = 600V$
Q_{gc} Gate-Collector Charge (turn-on)		190			$V_{GE} = 15V$
E_{on} Turn-On Switching Loss		1500		μJ	$T_J = 125^\circ\text{C}$
E_{off} Turn-Off Switching Loss		1220			Energy losses include tail and diode reverse recovery
E_{tot} Total Switching Loss		2720			
E_{on} Turn-On Switching Loss		950			$T_J = 25^\circ\text{C}$
E_{off} Turn-Off Switching Loss		850			Energy losses include tail and diode reverse recovery
E_{tot} Total Switching Loss		1800			
C_{ies} Input Capacitance		5100		pF	$V_{GE} = 0V$
C_{oes} Output Capacitance		490			$V_{CC} = 30V$
C_{res} Reverse Transfer Capacitance		200			$f = 1.0\text{ MHz}$
E_{rec} Reverse Recovery Energy of the Diode		1600		μJ	$T_J = 125^\circ\text{C}$
t_{rr} Diode Reverse Recovery Time		300		ns	$V_{CC} = 600V, I_C = 40A$
I_{rr} Peak Reverse Recovery Current		32		A	$V_{GE} = 15V, R_g = 5\Omega, L = 200\mu H$

Thermal- Mechanical Specifications

Parameters	Min	Typ	Max	Units
T_J Operating Junction Temperature Range	- 40		150	°C
T_{STG} Storage Temperature Range	- 40		125	
R_{thJC} Junction-to-Case	IGBT		0.35	°C/ W
	Diode		0.9	
R_{thCS} Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK)	Module	0.06		
Weight		66		g

Outline Table



Data and specifications subject to change without notice.
 This product has been designed for Industrial Level.
 Qualification Standards can be found on IR's Web site.